

49 7x7 FBGA, RoHS compliant, Package Weight

Device name: VS1003-B/LSR-ROHS

Document: A

Component	Weight (g)	Type	Material	%	Weight (g)
Chip	0.0126		Customer die	100.00	1.26E-02
Substrate	0.0026	49FBGA 7x7x1.45mm	R0049ST-05A (1E04971)	100.00	2.64E-03
Mold Compound	0.0915	SUMIKON EMEG760V	Fused Silica	95.00	8.69E-02
			Epoxy Resin	2.00	1.83E-03
			Phenol Resin	0.50	4.58E-04
			Antimony Trioxide	1.00	9.15E-04
			Brominated Epoxy Resin	1.00	9.15E-04
			Carbon Black	0.50	4.58E-04
Bonding Wires	0.00116	25μ NL51, 59 wires (1 wire ave weight ~1.9661E-05 gram)	Au	99.990	1.16E-03
			Ag	0.0008	9.28E-09
			Be	0.0010	1.16E-08
			Ca	0.0032	3.71E-08
			Cu	0.0005	5.80E-09
			Fe	0.0005	5.80E-09
			Mg	0.0005	5.80E-09
Epoxy	0.0055	Ablebond 2000B	Silver (Ag)	70.00	3.85E-03
			Epoxy Resin	5.00	2.74E-04
			Diester	10.00	5.50E-04
			Polymeric Resin	5.00	2.75E-04
			Functionalized Ester	10.00	5.50E-04
Solder Balls	0.0169	96.5Sn, 3Ag, 0.5Cu / 18 mils (1 solder ball ave wt ~ 3.4467E-04 gram)	Tin (Sn)	96.50	1.63E-02
			Silver (Ag)	3.00	5.07E-04
			Copper (Cu)	0.50	0.000085
Total Weight	0.1303 gram				0.1303 gram

\* Chemical Percent composition for epoxy, Au wires, mold compound & Solder balls are from supplier TDS & MSDS.